

**/ Revised record**

D	2018-7				
E	2018-10-16				
F	2019-3-13	2			
G	2020-1-8	2 3 6	$V_{GS(th)}$ 0.7~1.3V 0.65~1.3V $V_{GSS}$ $\pm 20$ 改 为 $\pm 12V$ ; $I_{GSS}$ 的条件 $V_{GS}=\pm 20V$ 改为 $V_{GS}=\pm 12V$ ;		





6

参数 Parameter	符号	数值
	$V_{sec}$	- V -

a s D

s

S



参数 Parameter	符号 Symbol	测试条件 Test Conditions		最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V$	$I_D=250\mu A$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=24V$	$V_{GS}=0V$			1.0	$\mu A$
		$V_{DS}=24V$	$V_{GS}=0V$			5.0	$\mu A$
		$T_J=55^\circ C$					
Gate-Body leakage current	$I_{GSS}$	$V_{GS}=\pm 12V$	$V_{DS}=0V$			100	nA
Gate Threshold Voltage							
On-state drain current				6			A

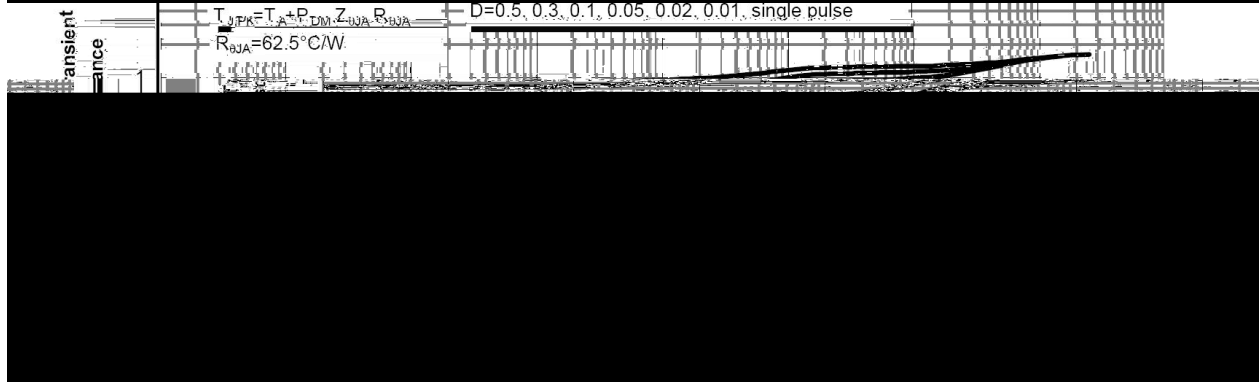
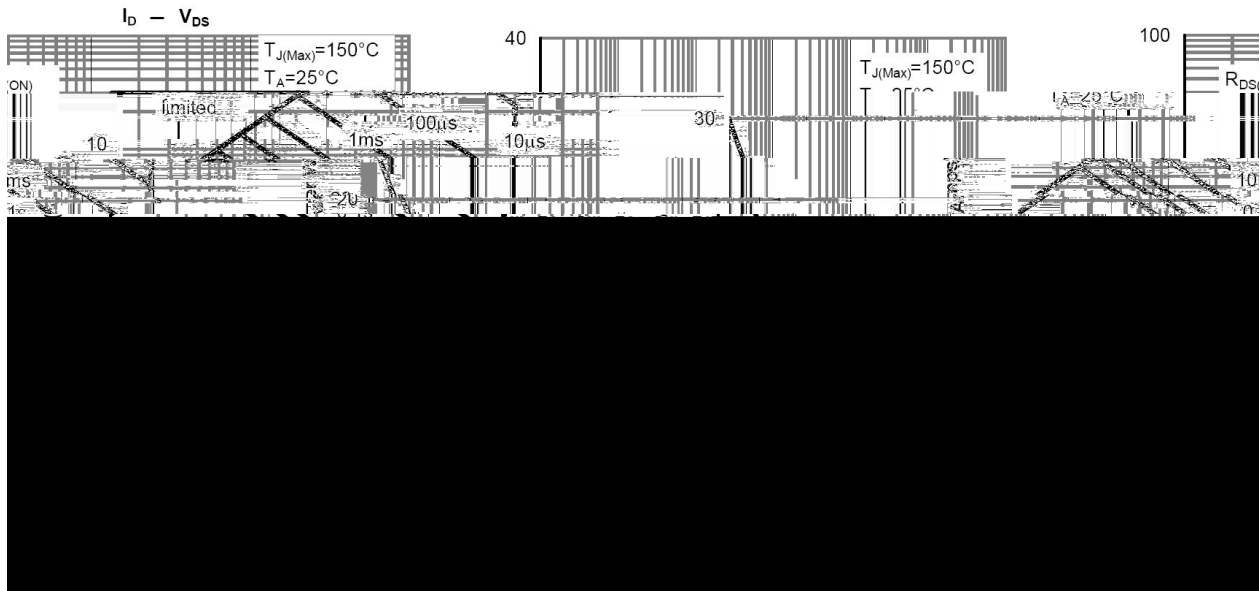
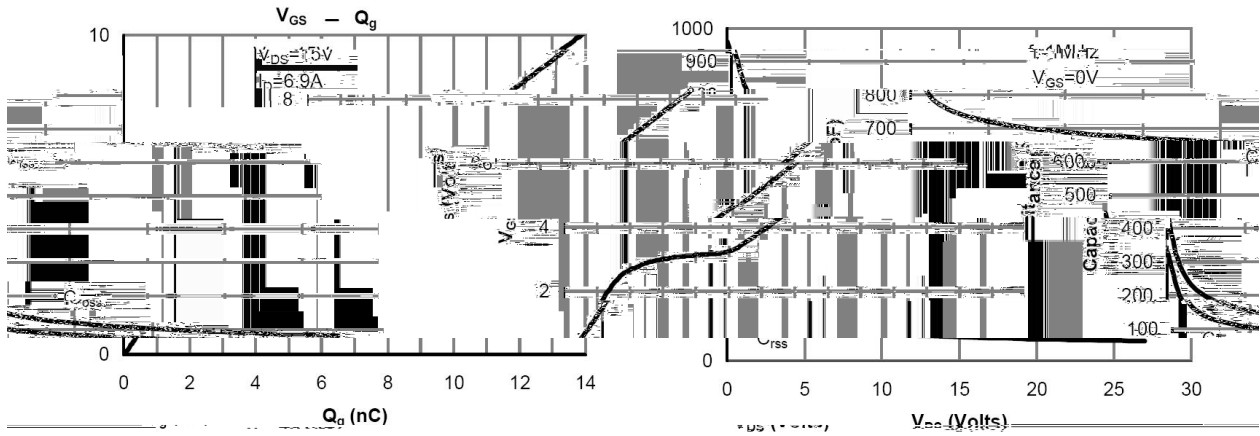
Static Drain-Source On-Resistance  $R_{DS(on)}$



N- / N-



**N- / N-CHANNEL Electrical Characteristic Curve**



参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}$				

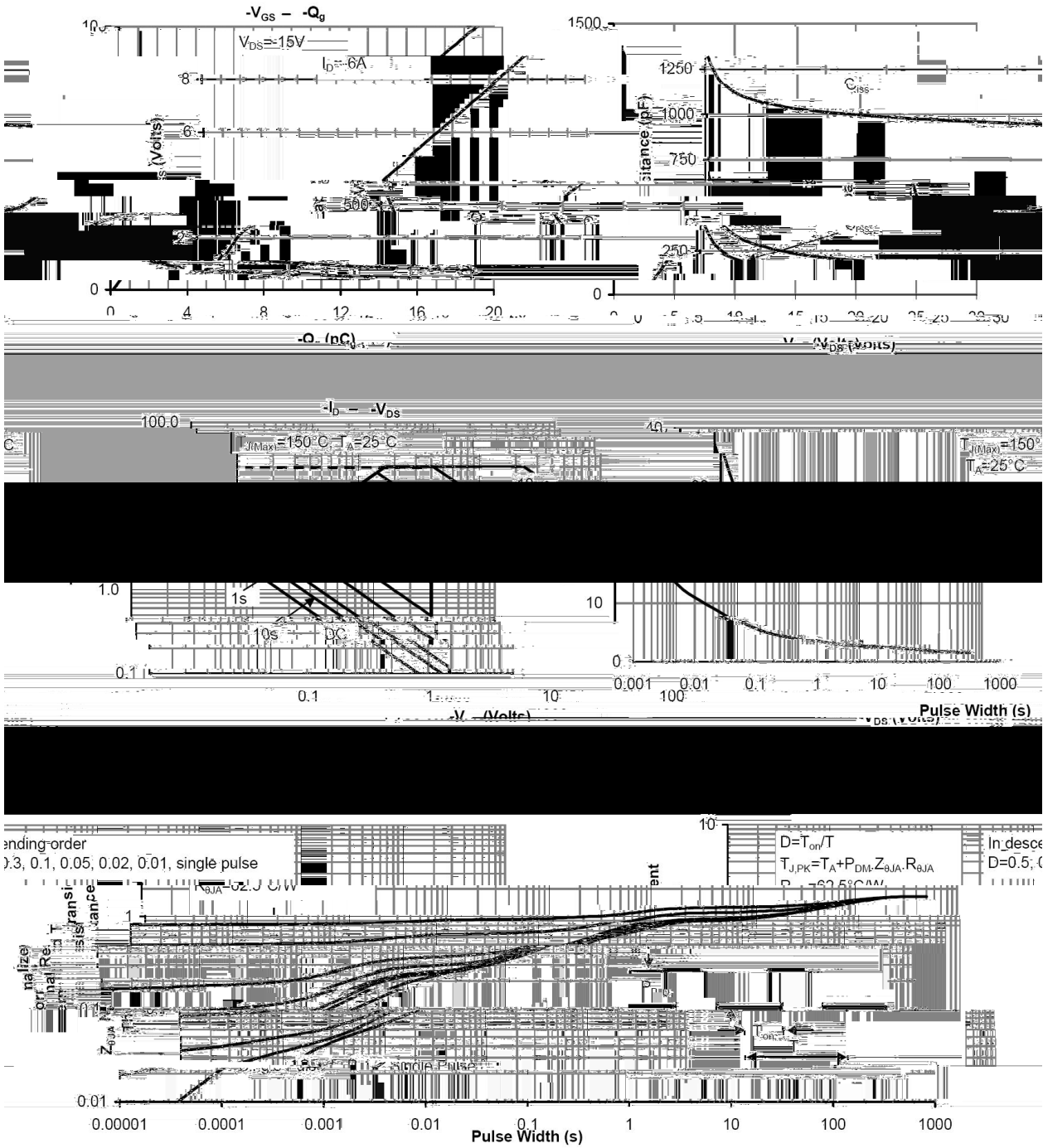


**P- / P-CHANNEL Electrical Characteristic Curve**





**P- / P-CHANNEL Electrical Characteristic Curve**

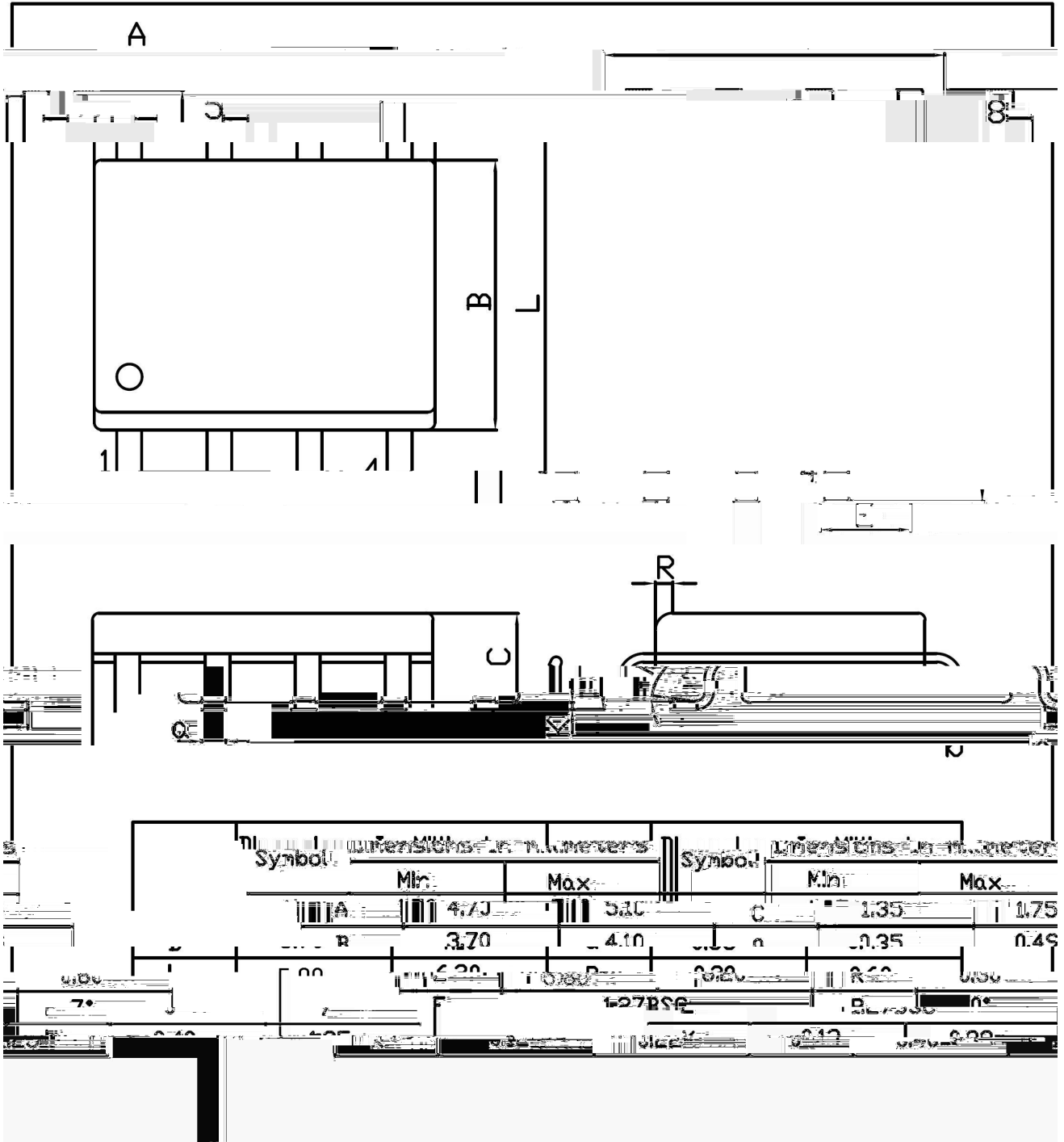




/ Package Dimensions

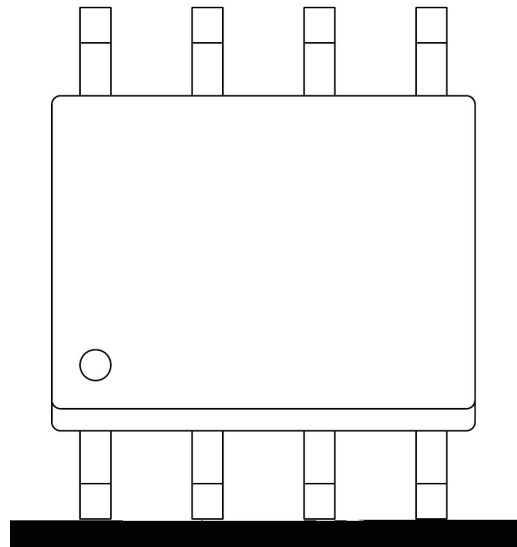
SOP-8

Unit:mm

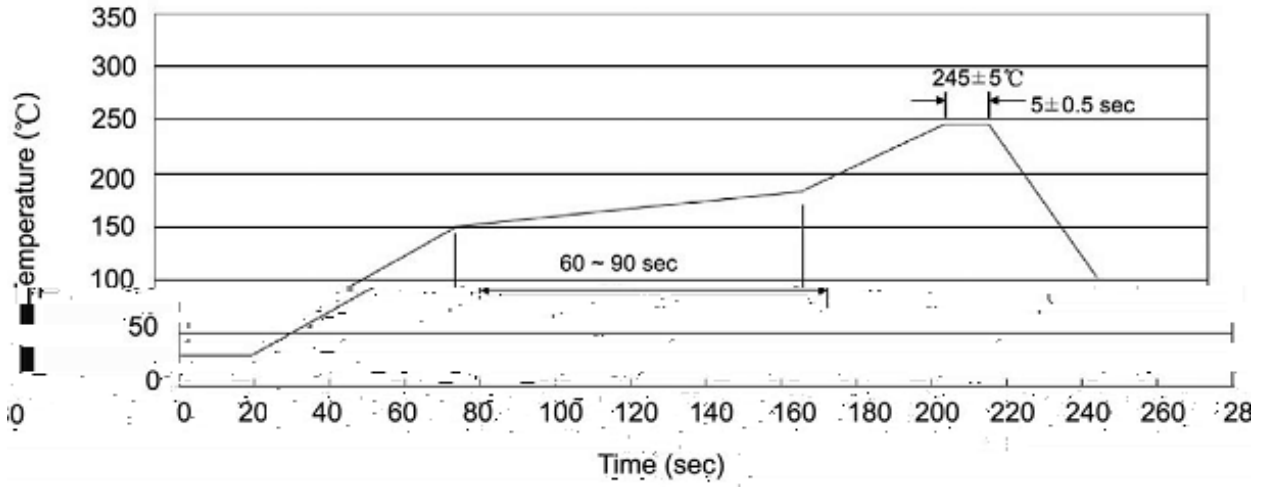




**/ Marking Instructions**



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预 温度 150~180°C , 时 60~90sec;
- 2、峰 温度 245±5°C , 时 说

Note:

- 1.Preheating:150~180°C, Time:60~90sec.